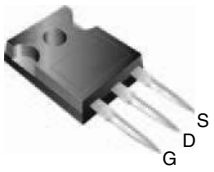
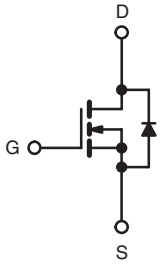
Power MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	500	
$R_{DS(on)}$ (Ω)	V_{GS} = 10 V	0.190
Q_g (Max.) (nC)	150	
Q_{gs} (nC)	44	
Q_{gd} (nC)	72	
Configuration	Single	

TO-247





N-Channel MOSFET

FEATURES

- Superfast Body Diode Eliminates the Need for External Diodes in ZVS Applications
- Lower Gate Charge Results in Simpler Drive Requirements
- Enhanced dV/dt Capabilities Offer Improved Ruggedness
- Higher Gate Voltage Threshold Offers Improved Noise Immunity
- Lead (Pb)-free Available

Available

RoHS* COMPLIANT

APPLICATIONS

- Zero Voltage Switching SMPS
- Telecom and Server Power Supplies
- Uninterruptible Power Supplies
- Motor Control Applications

ORDERING INFORMATION	
Package	TO-247
Lead (Pb)-free	IRFP23N50LPbF
	SiHFP23N50L-E3
SnPb	IRFP23N50L
	SiHFP23N50L

ABSOLUTE MAXIMUM RATINGS T_C = 25 °C, unless otherwise noted

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V_{DS}	500	V
Gate-Source Voltage			V_{GS}	± 30	
Continuous Drain Current	V_{GS} at 10 V	T_C = 25 °C	I_D	23	A
		T_C = 100 °C		15	
Pulsed Drain Current[a]			I_{DM}	92	
Linear Derating Factor				2.9	W/°C
Single Pulse Avalanche Energy[b]			E_{AS}	410	mJ
Repetitive Avalanche Current[a]			I_{AR}	23	A
Repetitive Avalanche Energy[a]			E_{AR}	37	mJ
Maximum Power Dissipation	T_C = 25 °C		P_D	370	W
Peak Diode Recovery dV/dt[c]			dV/dt	14	V/ns
Operating Junction and Storage Temperature Range			T_J, T_{stg}	- 55 to + 150	°C
Soldering Recommendations (Peak Temperature)	for 10 s			300[d]	
Mounting Torque	6-32 or M3 screw			10	lbf · in
				1.1	N · m

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. Starting T_J = 25 °C, L = 1.5 mH, R_G = 25 Ω, I_{AS} = 23 A (see fig. 12).
c. I_{SD} ≤ 23 A, dI/dt ≤ 430 A/µs, V_{DD} ≤ V_{DS}, T_J ≤ 150 °C.
d. 1.6 mm from case.

* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	40	°C/W
Case-to-Sink, Flat, Greased Surface	R_{thCS}	0.24	-	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.34	

SPECIFICATIONS T_J = 25 °C, unless otherwise noted

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 µA		500	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, I_D = 1 mA[d]		-	0.27	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA		3.0	-	5.0	V
Gate-Source Leakage	I_{GSS}	V_{GS} = ± 30 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 500 V, V_{GS} = 0 V		-	-	50	µA
		V_{DS} = 400 V, V_{GS} = 0 V, T_J = 125 °C		-	-	2.0	mA
Drain-Source On-State Resistance	$R_{DS(on)}$	V_{GS} = 10 V	I_D = 14 A[b]	-	0.190	0.235	Ω
Forward Transconductance	g_{fs}	V_{DS} = 50 V, I_D = 14 A[b]		12	-	-	S
Dynamic							
Input Capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1.0 MHz, see fig. 5		-	3600	-	pF
Output Capacitance	C_{oss}			-	380	-	
Reverse Transfer Capacitance	C_{rss}			-	37	-	
Output Capacitance	C_{oss}	V_{GS} = 0 V	V_{DS} = 1.0 V , f = 1.0 MHz	-	4800	-	
			V_{DS} = 400 V , f = 1.0 MHz	-	100	-	
Effective Output Capacitance	C_{oss} eff.		V_{DS} = 0 V to 400 V[c]	-	220	-	
Effective Output Capacitance (Energy Related)	C_{oss} eff. (ER)		V_{DS} = 0 V to 400 V[d]	-	160	-	
Internal Gate Resistance	R_G	f = 1 MHz, open drain		-	1.2	-	Ω
Total Gate Charge	Q_g	V_{GS} = 10 V	I_D = 23 A, V_{DS} = 400 V, see fig. 6 and 13[b]	-	-	150	nC
Gate-Source Charge	Q_{gs}			-	-	44	
Gate-Drain Charge	Q_{gd}			-	-	72	
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 250 V, I_D = 23 A, R_G = 6.0, V_{GS} = 10 V, see fig. 10[b]		-	26	-	ns
Rise Time	t_r			-	94	-	
Turn-Off Delay Time	$t_{d(off)}$			-	53	-	
Fall Time	t_f			-	45	-	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	23	A
Pulsed Diode Forward Current[a]	I_{SM}			-	-	92	
Body Diode Voltage	V_{SD}	T_J = 25 °C, I_S = 14 A, V_{GS} = 0 V[b]		-	-	1.5	V
Body Diode Reverse Recovery Time	t_{rr}	T_J = 25 °C	I_F = 23 A, dI/dt = 100 A/µs[b]	-	170	250	ns
		T_J = 125 °C		-	220	330	
Body Diode Reverse Recovery Charge	Q_{rr}	T_J = 25 °C		-	560	840	µC
		T_J =1 25 °C		-	980	1500	
Reverse Recovery Current	I_{RRM}	T_J = 25 °C		-	7.6	11	A
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)					

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. Pulse width ≤ 300 µs; duty cycle ≤ 2 %.
c. C_{oss} eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising fom 0 to 80 % V_{DS}.
d. C_{oss} eff. (ER) is a fixed capacitance that stores the same energy time as C_{oss} while V_{DS} is rising fom 0 to 80 % V_{DS}.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

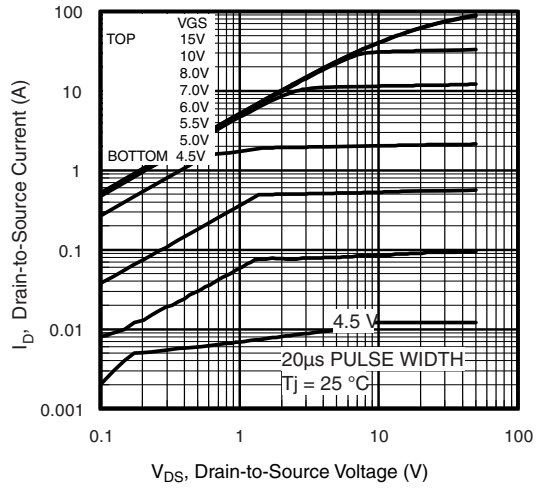


Fig. 1 - Typical Output Characteristics

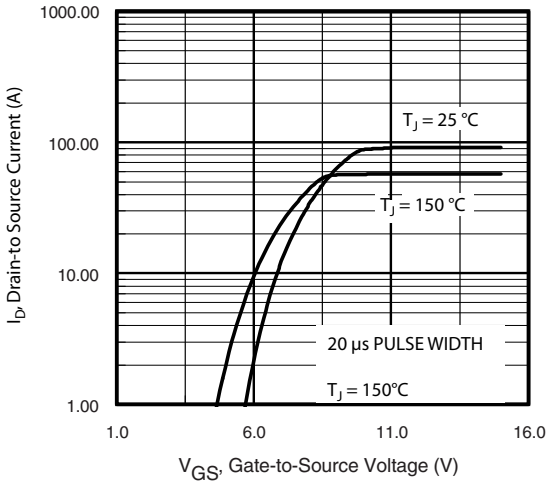


Fig. 3 - Typical Transfer Characteristics

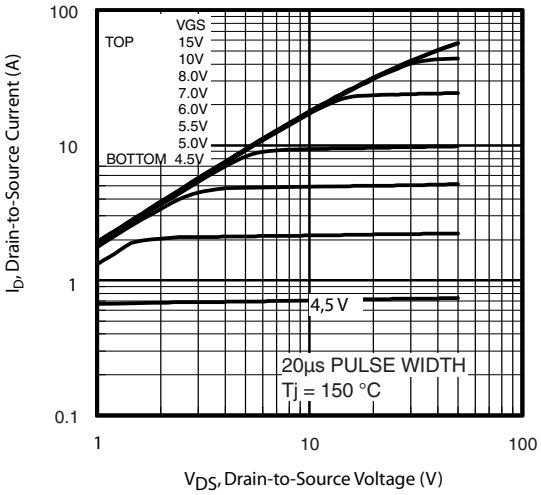


Fig. 2 - Typical Output Characteristics

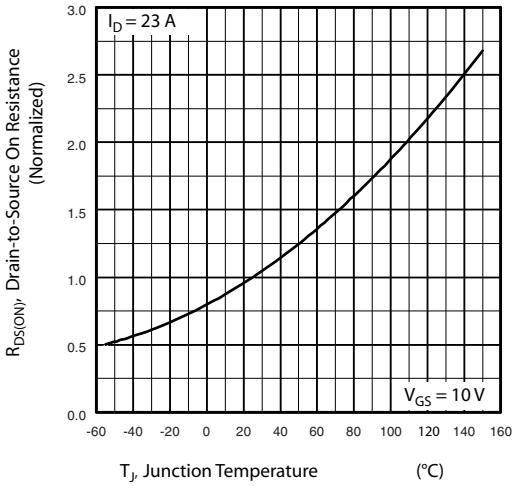


Fig. 4 - Normalized On-Resistance vs. Temperature

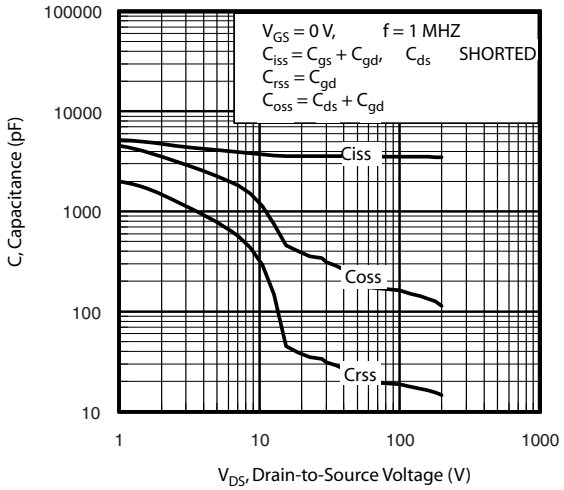


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

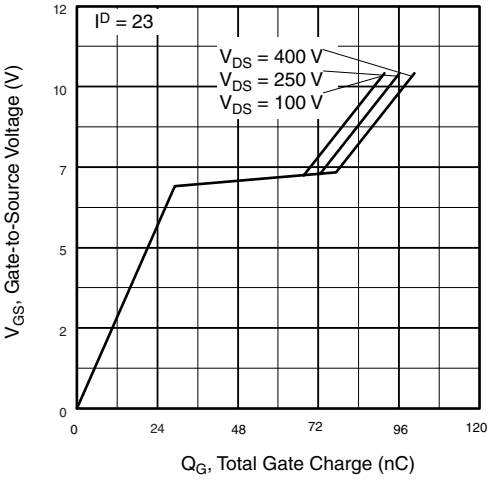


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

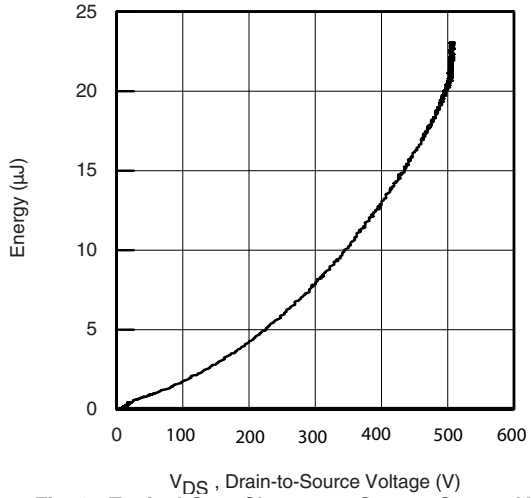


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

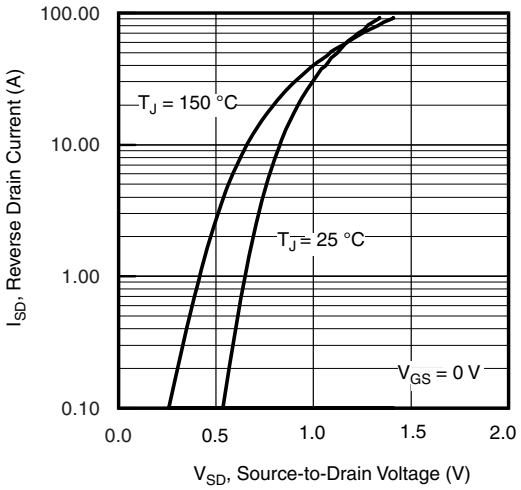


Fig. 8 - Typical Source-Drain Diode Forward Voltage

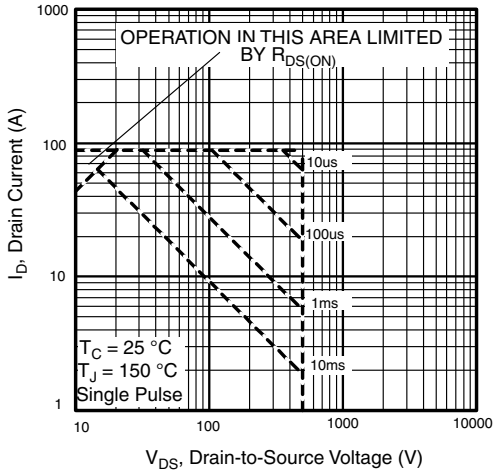


Fig. 9 - Maximum Safe Operating Area

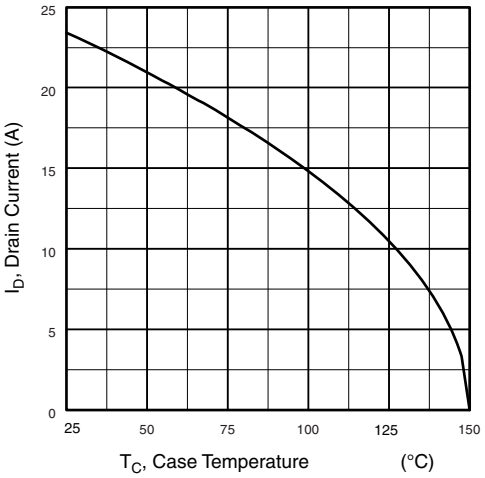


Fig. 10 - Maximum Drain Current vs. Case Temperature

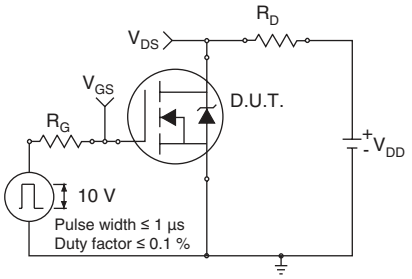


Fig. 11a - Switching Time Test Circuit

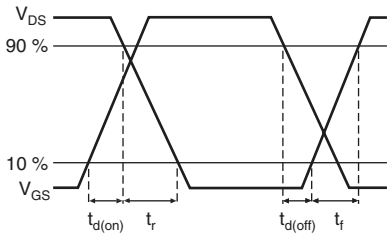


Fig. 11b - Switching Time Waveforms

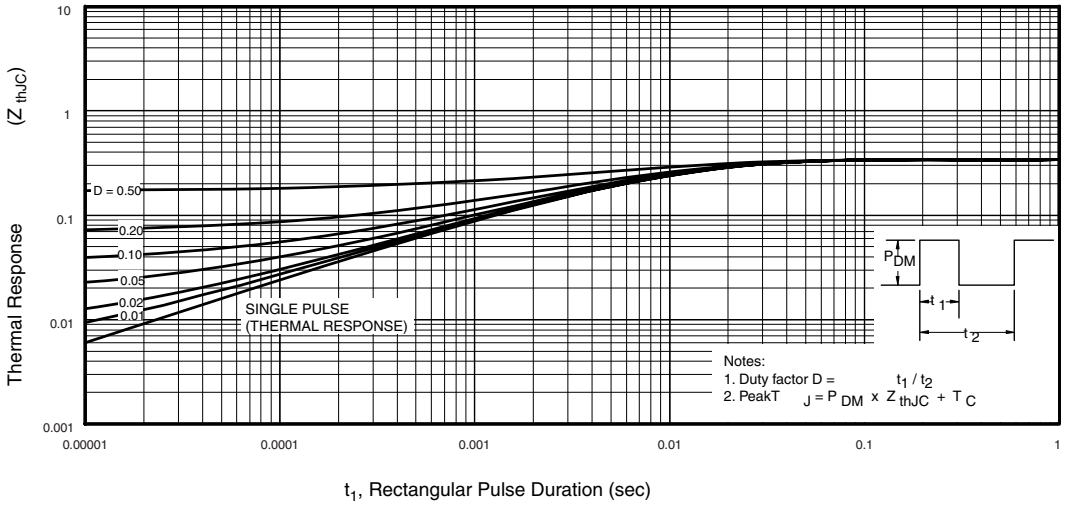


Fig. 12 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

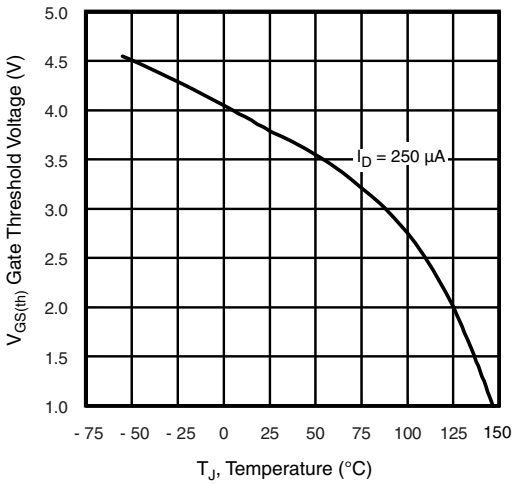


Fig. 13 - Threshold Voltage vs. Temperature

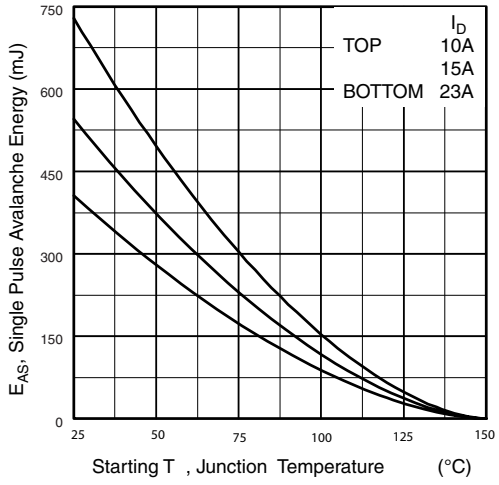


Fig. 14 - Maximum Avalanche Energy s. Drain Current

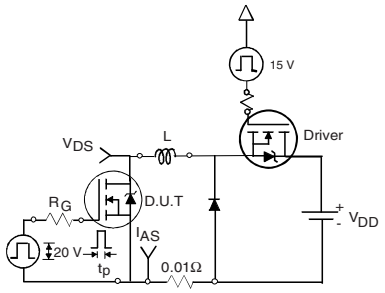


Fig. 15a - Unclamped Inductive Test Circuit

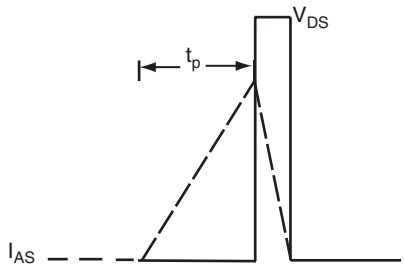


Fig. 15b - Unclamped Inductive Waveforms

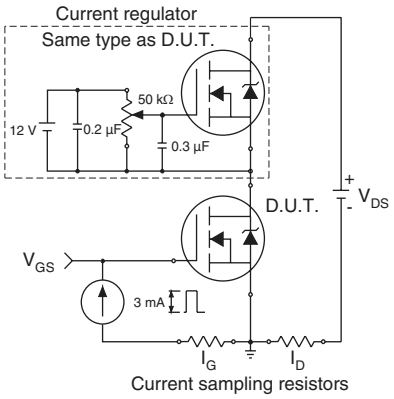


Fig. 16a - Gate Charge Test Circuit

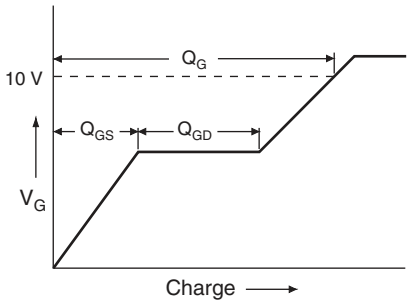
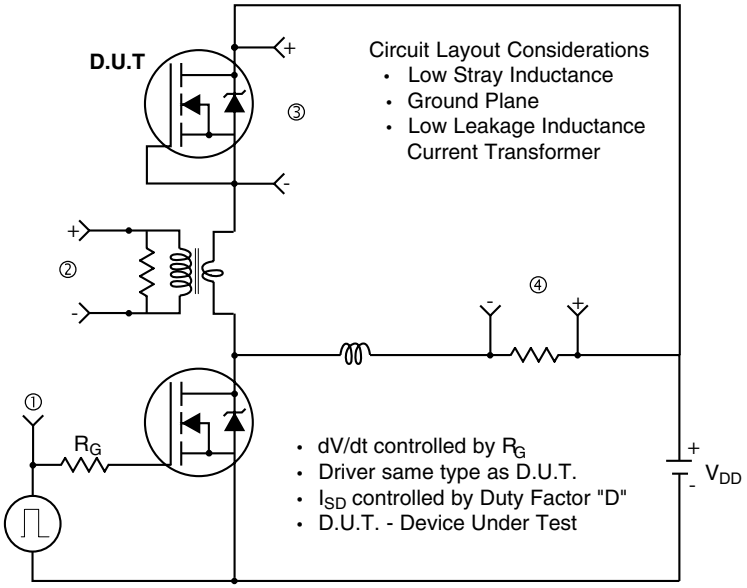
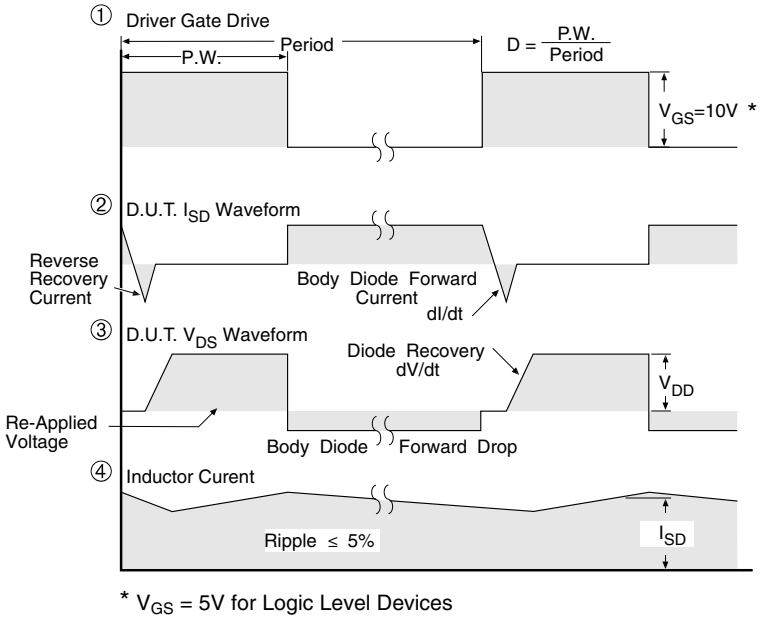


Fig. 16b - Basic Gate Charge Waveform

Peak Diode Recovery dV/dt Test Circuit





* V_{GS} = 5V for Logic Level Devices

Fig. 17 - For N-Channel

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